INTERPACK 2020 PROGRAM-AT-A-GLANCE

Pacific Time		Type	Moderators & Speakers	Title	Company
Day 0 - Monday, 26th October 2020					
Workshop Session Chaired by Anna Prakash (Intel Corporation)					
4:00 PM	6:00 PM	Workshop	Priyanka Dobriyal Abigail Agwai Oliver Chen Elaina Ashton	(AI in AD) Introduction to Robotics, Self-Driving Cars and AI with Drones	Intel Corporation & Arizona State University
6:00 PM	6:15 PM	Q&A			
Day 1 - Tuesday, 27th October 2020					
7:45 AM	8:00 AM	Welcome	Thomas Costabile (ASME Executive Director/CEO)	Welcome to ASME InterPACK 2020 Virtual Event	ASME
Room 1: Keynote Session Chaired by Thomas Costabile and Baris Dogruoz					
8:00 AM	8:50 AM	Keynote	Suresh Ramalingam	Challenges and Opportunities in Next Generation of Advanced Packaging	Xilinx
8:50 AM	9:00 AM	Q&A			
9:00 AM	9:10 AM	Break	**Exhibitor Corner - Presentation by Invensense/TDK**		
Panel Sessions					
Room 1: Chaired by Gamal Refai-Ahmed (Xilinx) and Leila Choobineh (SUNY Polytechnic Institute)					
9:10 AM	10:30 AM	Panel	Gamal Refai-Ahmed Leila Choobineh Amr Helmy Bahgat Sammakia Ravi Mahajan Suresh Ramalingam	HIR Challenges and Opportunity	Xilinx SUNY Polytechnic Institute University of Toronto Binghamton University Intel Corporation Xilinx
10:30 AM	10:40 AM	Q&A			
Room 2: Chaired by Dan Hines (University of Maryland)					
9:10 AM	10:30 AM	Panel	Dan Hines Brett Walker Ethan Secor Yuri Didenko Dave Pope Jeffrey Dee	Materials for Additive Manufacturing	University of Maryland Electroninks Iowa State University UTDots NovaCentrix DuPont
10:30 AM	10:40 AM	Q&A			
Room 3: Industry, National Laboratory, and Academia Posters - Session 1 Chaired by Cheng Chen (Facebook)					
9:10 AM	10:10 AM	Presentations	Poster Presentations and Q&A		
10:10 AM	10:40 AM	Q&A			
10:40 AM	10:50 AM	Break	Coffee Break / Exhibitor Corner		
Panel Sessions					
Room 1: Chaired by Victor Chiriac (Global Cooling Technology Group)					
10:50 AM	12:10 PM	Panel	Victor Chiriac Kinzy Jones, Jr. YC Lee Matthew Dalton Amy Marconnet Luca Amalfi	Advances in Wearable/Wireless Flexible Electronics: Thermal and Mechanical	Global Cooling Technology Group Magic Leap Kelvin Tech WP-AFRL Purdue University Nokia/Bell Labs
12:10 PM	12:20 PM	Q&A			
Room 2: Chaired by Leila Choobineh (SUNY Polytechnic Institute)□					
10:50 AM	12:40 PM	Panel	Leila Choobineh Tannaz Harirchian Jelena Srebric Anna M Prakash Nesrin Ozalp Elham Maghsoudi Shelby Nelson	Women in Engineering	SUNY Polytechnic Institute Intel Corporation University of Maryland Intel Corporation Purdue University Northwest NASA Jet Propulsion Laboratory Mosaic Microsystems, LLC
12:40 PM	12:50 PM	Q&A			
Room 3: Industry, National Laboratory, and Academia Posters - Session 2 Chaired by Cheng Chen (Facebook)					
10:50 AM	11:50 AM	Presentations	Poster Presentations and Q&A		
11:50 AM	12:20 PM	Q&A			
12:50 PM	1:50 PM	Tribute	**Room 1: Tribute to Professor Avram (Avi) Bar-Cohen Organized by Madhu Iyengar (Google) and Dereje Agonafer (UTA)**		
Room 1: Tutorial Chaired by David Huitink (University of Arkansas)					
1:50 PM	3:40 PM	Tutorial	Ephraim Suhir	Probabilistic DfR in Electronics & Photonics & Its Role in Making a Viable IC Package into a Reliable Product	Portland State University
3:40 PM	3:50 PM	Q&A			
InterPACK Organization Zoom Meetings					
4:00 PM	5:00 PM	ASME EPPD Executive Committee Meeting (By Invitation Only)			
5:00 PM	6:00 PM	InterPACK	Ricky Lee	JEP Meeting	Hong Kong University of Science and Technology
Day 2 - Wednesday, 28th October 2020					
7:45 AM	8:00 AM	ASME EPPD	Amy Spencer Fleischer	ASME EPPD Introduction	California Polytechnic University
Room 1: Keynote Session Chaired by Amy Spencer Fleischer (California Polytechnic University) and Jin Yang (Intel)					
8:00 AM	8:50 AM	Keynote	Bongtae Han	Quantitative Prediction of Warpage after Molding Processes: Is It a Myth?	CALCE - University of Maryland
8:50 AM	9:00 AM	Q&A			
9:00 AM	9:10 AM	Break	Coffee Break / Exhibitor Corner		
Panel Sessions					
Room 1: Chaired by Pradeep Lall (Auburn University)					
9:10 AM	10:30 AM	Panel	Pradeep Lall Bryan Germann Mike Newton Don Veri Doug Schardt	Printing Technologies for Additive Electronics	Auburn University Optomec nScrypt SUSS Komori America
10:30 AM	10:40 AM	Q&A			
Room 2: Chaired by: Victor Chiriac (Global Cooling Technology Group)					
9:10 AM	10:30 AM	Panel	Victor Chiriac Ravi Mahajan Hiroyuki Ryoson John Thome Mark Earnshaw Amy Marconnet Don Le	Mobile, IoT and Compute Device Applications: Thermal and Mechanical Challenge	Global Cooling Technology Group Intel Corporation Dexerials ex-EPFL Nokia Bell Labs Purdue University Qualcomm
10:30 AM	10:40 AM	Q&Q			
10:40 AM	10:50 AM	Break	Coffee Break / Exhibitor Corner		
Panel Sessions					
Room 1: Chaired by Fang Luo (Stonybrook)					
10:50 AM	12:10 PM	Panel	Fang Luo Michael Fish Charles Lents Peter DeBock G.Q. Lu	Potential of Additive Manufacturing for Power Electronics	Stonybrook Army Research Laboratory RTX DOE Virginia Tech
12:10 PM	12:20 PM	Q&A			
Room 2: Chaired by Jimil Shah (3M) and Saket Karajgikar (Facebook)					
10:50 AM	12:10 PM	Workshop	Dharmesh Jani Archna Haylock Rob Coyle Caleb Lusk Bapi Vinnakota	Open Compute Project Workshop	Facebook OCP PCX Rittal Broadcom
12:10 PM	12:20 PM	Q&A			
12:20 PM	1:20 PM	Presentation	**Room 1: InterPACK Achievement Award Presentation Chaired by Jin Yang (Intel)**		
		Presenter and Award Winner	Cristina H. Amon	Thermal Management of EVs with an Overview of Engineering Challenges and Our Work on Batteries and Chargers	University of Toronto
1:20 PM	1:50 PM	Q&A			
Room 1: Tutorial Chaired by Doug DeVoto (NREL)					
1:50 PM	3:40 PM	Tutorial	Doug DeVoto Gilberto Moreno Sukwon Choi	Thermal and Reliability Aspects of Automotive Power Electronics: Current Status and Future Trends	National Renewable Energy Laboratory & Pennsylvania State University
3:40 PM	3:50 PM	Q&A			
InterPACK Organization Zoom Meetings					
4:00 PM	5:00 PM	K-16 Committee Meeting			
5:00 PM	6:00 PM	InterPACK	InterPACK Advisory Committee	InterPACK Advisory Committee Meeting	By Invitation Only
Day 3 - Thursday, 29th October 2020					
7:45 AM	8:00 AM	ASME EPPD	Amy Spencer Fleischer	ASME EPPD Introduction	California Polytechnic University
Room 1: Keynote Session Chaired by Amy Spencer Fleischer (California Polytechnic University) and Przemek Gromala (Bosch)					
8:00 AM	8:50 AM	Keynote	Scott Miller	Flexible Hybrid Electronics Manufacturing for Integrated Systems	NextFlex
8:50 AM	9:00 AM	Q&A			
9:00 AM	9:10 AM	Break	Coffee Break / Exhibitor Corner		
Panel and Workshop Sessions					
Room 1: Chaired by Ben Leever (Air Force Research Laboratory)					
9:10 AM	10:30 AM	Panel	Ben Leever Mary Herndon John Rogers Stephen Gonya David Shaddock	Aerospace Electronics	Air Force Research Laboratory Raytheon Lockheed Martin Boeing GE
10:30 AM	10:40 AM	Q&A			
Room 2: Chaired by Bill Bottoms (3MTS) and Ravi Mahajan (Intel) Facilitators: Gamal Refai-Ahmed, Amr Helmy, Bill Chen, Madhusudan Iyengar, Weihua Tang. Abhijit Dasgupta					
9:10 AM	10:30 AM	Workshop	John Shalf Antai Xu Ali Heydari John Bowers	HIR Workshop - Part 1	Lawrence Berkeley National Laboratory Xilinx Corporation Nvidia Institute for Energy Efficiency - UC-Santa Barbara
10:30 AM	10:40 AM	Q&A			
10:40 AM	10:50 AM	Break	Coffee Break / Exhibitor Corner		
Workshop Sessions and Awards Ceremony					
Room 1: Chaired by Darshan Pahinkar (FIT) and Jimil Shah (3M)					
10:50 AM	12:10 PM	Workshop	Darshan Pahinkar Ronald Warzoha Ankur Jain Lauren Boteler	K-16 Mentoring Workshop	K-16 Committee
12:10 PM	12:20 PM	Q&A			
Room 2: Chaired by Bill Bottoms (3MTS) and Ravi Mahajan (Intel) Facilitators: Gamal Refai-Ahmed, Amr Helmy, Bill Chen, Madhusudan Iyengar, Weihua Tang, Abhijit Dasgupta					
10:50 AM	12:10 PM	Workshop	John Shalf Antai Xu Ali Heydari John Bowers	HIR Workshop - Part 2	Lawrence Berkeley National Laboratory Xilinx Corporation Nvidia Institute for Energy Efficiency - UC-Santa Barbara
12:10 PM	12:20 PM	Q&A			
12:20 PM	12:50 PM	Room 1: Award Ceremony	Chaired by Dereje Agonafer	Allan Kraus Thermal Management Medalist	University of Texas at Arlington
12:50 PM	1:50 PM		Chaired by Jin Yang	Other Awards Ceremony	Intel Corporation
Room 1: Workshop Chaired by Jimil Shah (3M) and Saket Karajgikar (Facebook)					
1:50 PM	3:40 PM	Workshop	Saket Karajgikar Dereje Agonafer Amy Spencer Fleischer	Career Development Workshop	Facebook University of Texas at Arlington California Polytechnic University
3:40 PM	3:50 PM	Q&A			
InterPACK Organization Zoom Meeting					
4:00 PM	5:00 PM	InterPACK Summary and Planning Meeting			